

FIG. 1

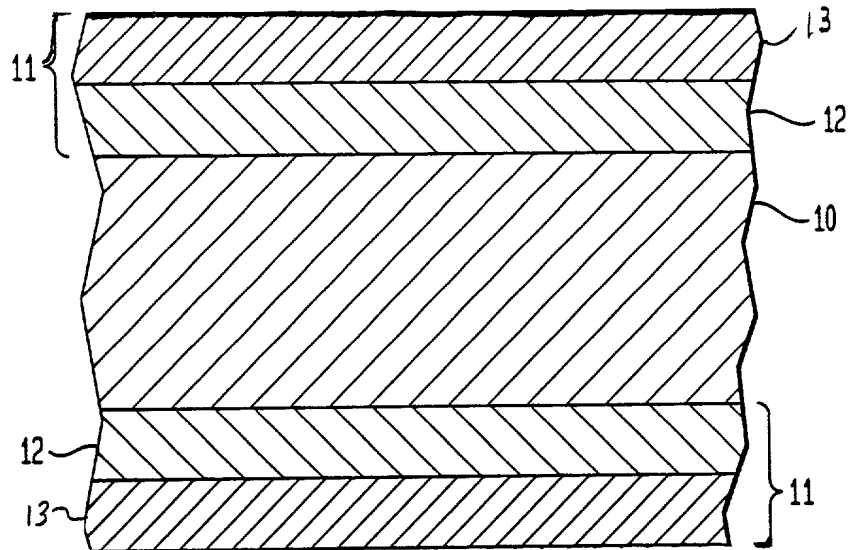


FIG. 2

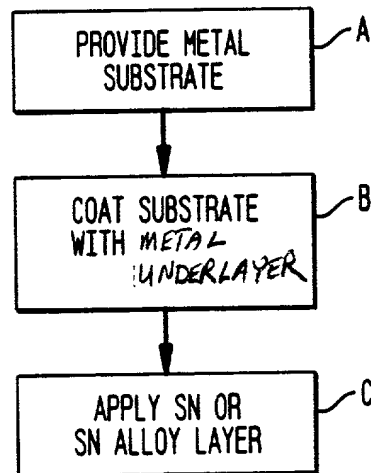


FIG. 3

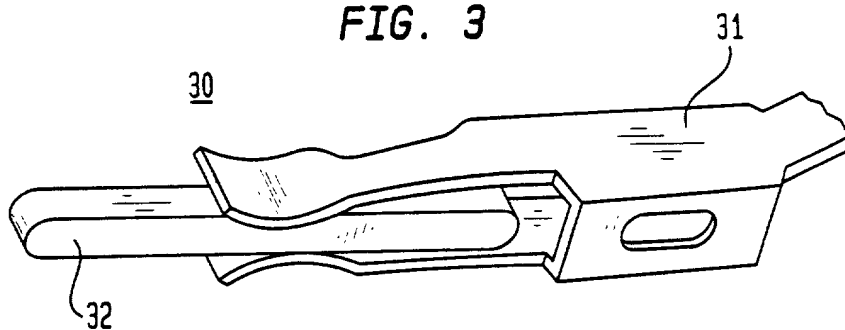


FIG. 4

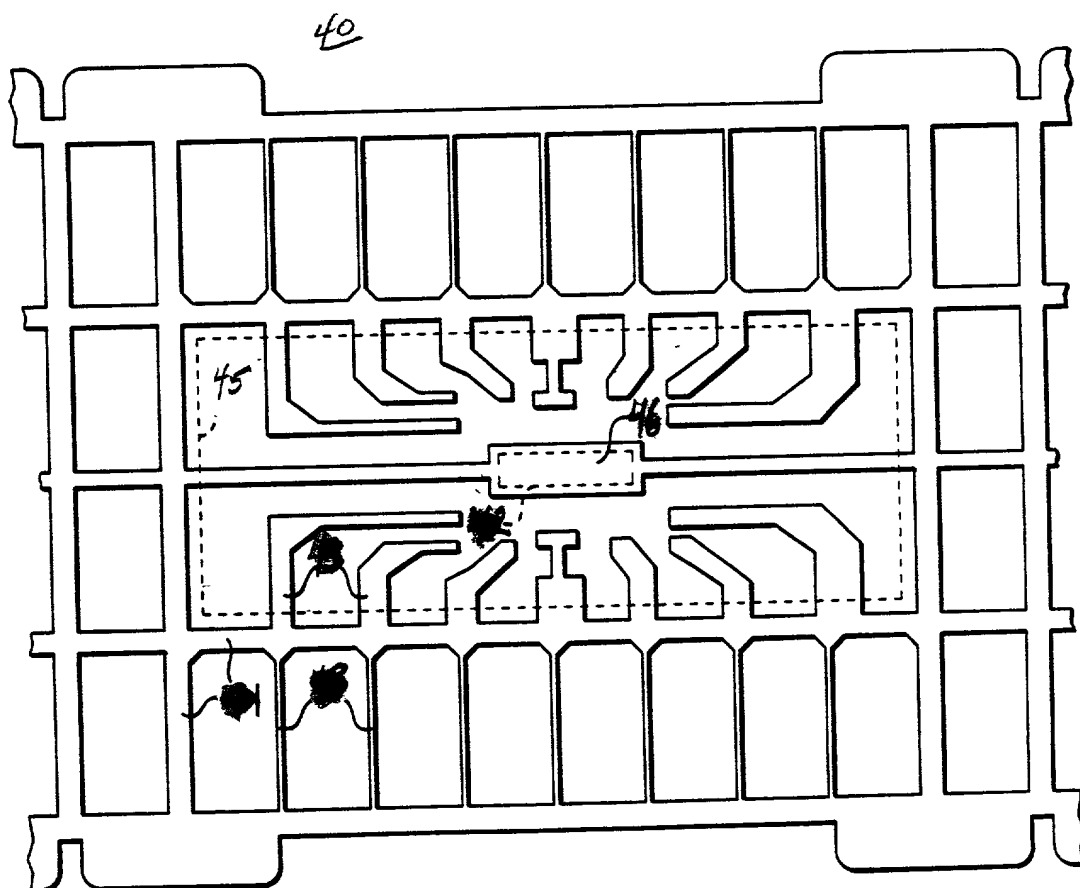


Figure 1 consists of four SEM micrographs labeled a, b, c, and d, showing the surface morphology of a 100% Sn whisker solder. Each image displays a central solder pad with numerous whiskers extending from its surface. The whiskers are thin, needle-like structures. The background is a rough, textured surface. Each image includes a 5 µm scale bar and a data table at the bottom.

Micrograph a:

Mag	09/1800	pa	Tilt
20.0 x	11.13.10	71.0	45.0

5 µm
Sn whisker analysis

Micrograph b:

Mag	09/1800	pa	Tilt
20.0 x	12.28.10	39.0	45.0

5 µm
Sn whisker analysis

Micrograph c:

Mag	09/1800	pa	Tilt
20.0 x	12.28.10	39.0	45.0

5 µm
Sn whisker analysis

Micrograph d:

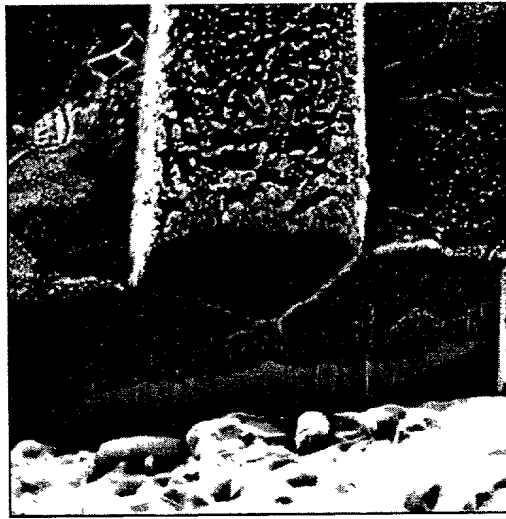
Mag	09/1800	pa	Tilt
20.0 x	12.28.10	39.0	45.0

5 µm
Sn whisker analysis

5D

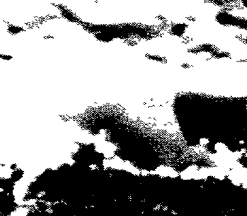
09837027-062204

Fig. 6



The diagram shows a large, dark, irregularly shaped region labeled 'a' and a smaller, dark, rectangular region labeled 'b'. A line connects the two regions, indicating a relationship or transition between them. The background is filled with a dense, granular texture.

b

[illegible]